ABSTRACT

A highly efficient method for cleaning a substrate, whereby in the cleaning of the substrate, ① in a short time, ② both particle contaminants and metal contaminants can be removed, and ③ a problem associated therewith, such as re-deposition of contaminants or a dimensional change due to etching, can be remarkably reduced, and which has the following characteristics.

A method for cleaning a surface of a substrate, which comprises at least the following steps (1) and (2), wherein the step (2) is carried out after carrying out the step (1):

Step (1): A cleaning step of cleaning the surface of the substrate with an alkaline cleaning agent containing a complexing agent, and

Step (2): A cleaning step employing a cleaning agent having a hydrofluoric acid content C (wt%) of from 0.03 to 3 wt%, wherein the cleaning time t (seconds) of the substrate with said cleaning agent is at most 45 seconds, and C and t satisfy the relationship of $0.25 \leqq tC^{1.29} \leqq 5$.